L Number	Hits	Search Text	DB	Time stamp
19	343	(702/94).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:21
20	16	((702/94).CCLS.) and (align$7 with mark$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:21
21	189	(702/95).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:22
22	4	((702/95).CCLS.) and (align$7 with mark$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 16:00
25	709	(702/150).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:32
26	18	((702/150).CCLS.) and (align$7 with mark$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:32
27	251	(702/151).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:53
28	6	((702/151).CCLS.) and (align$7 with mark$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:54
47	210	(702/152).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:54
48	3	((702/152).CCLS.) and (align$7 with mark$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:54
49	173	(702/153).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:55
54	14	((undetect$4 or (un adj detect$5)) with (align$6 near mark$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:19
55	34	((alignment$1 near mark$1) with regist$8) and ((alignment$1 near mark$1) with (image$1 or imaging$3)) and (mark$1 with (substrate$1 or semiconductor or (semi adj conductor$1) or wafer$1)) and pattern$1 and (mark$5 with reference$1) and ((mark$1 or image$1) near (portion$1 or part$1 or partial$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:02

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58	0	(("not" adj detect$5) with (align$6 near mark$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:20
63	661	(356/614,620).CCLS. .	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 16:00
64	53	((356/614,620).CCLS.) and (align$7 with mark$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 16:00
65	42	((356/614,620).CCLS.) and (align$7 with mark$1) and (image$1 or imaging)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 16:31
66	1852	(382/141,144,151).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 16:31
67	129	((382/141,144,151).CCLS.) and (align$7 with mark$1) and (image$1 or imaging)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 16:31
68	80	((382/141,144,151).CCLS.) and (align$7 near mark$1) and (image$1 or imaging)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 16:32
-	4	"6571196"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 09:11
-	38	KOSUGE-SHOGO	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 09:15
-	1001	(hitachi).asn. and (align$7 with mark$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:16
-	744	(hitachi).asn. and (align$7 near mark$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 09:17
-	312	(hitachi).asn. and (align$7 near mark$1) and ((detect$6 or determin$7) with position$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 09:17
-	49	(hitachi).asn. and (align$7 near mark$1) and ((detect$6 or determin$7) with position$1) and register$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 09:18
-	3	(hitachi).asn. and (align$7 near mark$1) and ((detect$6 or determin$7) with position$1) and register$4 and video	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 09:21

-	2	(hitachi).asn. and (align$7 near target$1) and ((detect$6 or determin$7) with position$1) and register$4 and video	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 09:22
-	289	(align$7 near (target$1 or mark$1)) and ((detect$6 or determin$7) with position$1) and register$4 and video	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 09:23
-	235	(align$7 near (target$1 or mark$1)) and ((detect$6 or determin$7) with position$1) and register$4 and video and pattern$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 10:17
-	24	(align$7 near (target$1 or mark$1)) and ((detect$6 or determin$7) with position$1) and register$4 and video and pattern$1 and (line adj width$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 09:25
-	3165	(align$7 near (target$1 or mark$1)) and ((detect$6 or determin$7) with position$1) and (image$1 or imaging or video) and pattern$1 and (semiconductor$1 or (semi adj conductor$1) or wafer$1 or substrate$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 10:23
-	1660	(align$7 near (target$1 or mark$1)) and ((detect$6 or determin$7) with position$1) and ((image$1 or imaging or video) with mark$1) and pattern$1 and (semiconductor$1 or (semi adj conductor$1) or wafer$1 or substrate$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 10:24
-	1018	(align$7 near (target$1 or mark$1)) and ((detect$6 or determin$7) with position$1) and ((image$1 or imaging or video) with mark$1) and pattern$1 and (semiconductor$1 or (semi adj conductor$1) or wafer$1 or substrate$1) and (mark$1 with reference$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 10:32
-	102	(align$7 near (target$1 or mark$1)) and ((detect$6 or determin$7) with position$1) and ((image$1 or imaging or video) with mark$1) and pattern$1 and (semiconductor$1 or (semi adj conductor$1) or wafer$1 or substrate$1) and (mark$1 with reference$1) and (register$6 with mark$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 11:16
-	180	(align$7 near (target$1 or mark$1)) and ((detect$6 or determin$7) with position$1) and ((image$1 or imaging or video) with mark$1) and pattern$1 and (semiconductor$1 or (semi adj conductor$1) or wafer$1 or substrate$1) and (mark$1 with reference$1) and (regist$8 with mark$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 10:39
-	179	(align$7 near (target$1 or mark$1)) and ((detect$6 or determin$7) with position$1) and ((image$1 or imaging or video) with mark$1) and pattern$1 and (semiconductor$1 or (semi adj conductor$1) or wafer$1 or substrate$1) and (mark$1 with reference$1) and ((register$4 or registration) with mark$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 11:19

–	117	(align$7 near (target$1 or mark$1)) and ((detect$6 or determin$7) with position$1) and ((image$1 or imaging or video) with mark$1) and pattern$1 and (semiconductor$1 or (semi adj conductor$1) or wafer$1 or substrate$1) and (mark$1 with reference$1) and ((register$4 or registration) with (align$6 near (mark$1 or target$1)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 11:14
–	52	(align$7 near (target$1 or mark$1)) and ((detect$6 or determin$7) with position$1) and ((image$1 or imaging or video) with mark$1) and pattern$1 and (semiconductor$1 or (semi adj conductor$1) or wafer$1 or substrate$1) and (mark$1 with reference$1) and (register$6 with mark$1) and ((line adj width$1) or inspect$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 11:16
–	96	(align$7 near (target$1 or mark$1)) and ((detect$6 or determin$7) with position$1) and ((image$1 or imaging or video) with mark$1) and pattern$1 and (semiconductor$1 or (semi adj conductor$1) or wafer$1 or substrate$1) and (mark$1 with reference$1) and ((register$4 or registration) with mark$1) and ((part or parts or partial$4) with mark$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 11:25
–	54	(align$7 near (target$1 or mark$1)) and ((detect$6 or determin$7) with position$1) and ((image$1 or imaging or video) with mark$1) and pattern$1 and (semiconductor$1 or (semi adj conductor$1) or wafer$1 or substrate$1) and (mark$1 with reference$1) and ((register$4 or registration) with mark$1) and ((part or parts or partial$4) near3 mark$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 11:26
–	74	(align$7 near (target$1 or mark$1)) and ((detect$6 or determin$7) with position$1) and ((image$1 or imaging or video) with mark$1) and pattern$1 and (semiconductor$1 or (semi adj conductor$1) or wafer$1 or substrate$1) and (mark$1 with reference$1) and ((register$4 or registration) with mark$1) and ((part or parts or partial$4) near3 (mark$1 or image$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 12:55
–	6	(align$7 near (target$1 or mark$1)) and ((detect$6 or determin$7) with position$1) and ((image$1 or imaging or video) with mark$1) and pattern$1 and (semiconductor$1 or (semi adj conductor$1) or wafer$1 or substrate$1) and (mark$1 with reference$1) and ((register$4 or registration) with mark$1) and (((part or parts or partial$4) near3 (mark$1 or image$1)) with regist$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 13:09
–	10	(align$7 near (target$1 or mark$1)) and ((detect$6 or determin$7) with position$1) and ((image$1 or imaging or video) with mark$1) and pattern$1 and (semiconductor$1 or (semi adj conductor$1) or wafer$1 or substrate$1) and (mark$1 with reference$1) and ((register$4 or registration) with mark$1) and (((part or parts or partial$4) with (mark$1 or image$1)) with regist$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 13:19

-	0	((image or imaging) with (alignment near mark$1) with reference$1) and (regist$9 with (alignment near mark$1) with (part$1 or partial$4)) and ((image or imaging) with (alignment near mark$1) with inspect$1) and ((detect$6 or determin$5) with position$1 with (alignment near mark$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 13:24
-	0	((image or imaging) with mark$1 with reference$1) and ((regist$9 with mark$1) with (part$1 or partial$4)) and ((image or imaging) with mark$1 with inspect$1) and ((detect$6 or determin$5) with position$1 with mark$1) and (align$6 near mark$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 13:27
-	2	((image or imaging) with mark$1 with reference$1) and ((regist$9 with mark$1) with (part$1 or partial$4)) and ((image or imaging) with (mark$1 and inspect$1)) and ((detect$6 or determin$5) with (position$1 and mark$1)) and (align$6 near mark$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 13:30
-	4	(((image or imaging) with mark$1) with reference$1) and ((regist$9 with (mark$1 or image$3)) with (part$1 or partial$4)) and (((image or imaging) with inspect$6) with mark$1) and (((detect$6 or determin$5) with position$1) with mark$1) and (align$6 near mark$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 13:39
-	36	(line near width$1) and ((alignment$1 near mark$1) with regist$8) and ((alignment$1 near mark$1) with (image$1 or imaging$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 15:14
-	145	((alignment$1 near mark$1) with regist$8) and ((alignment$1 near mark$1) with (image$1 or imaging$3)) and (mark$1 with (substrate$1 or semiconductor or (semi adj conductor$1) or wafer$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 15:17
-	93	((alignment$1 near mark$1) with regist$8) and ((alignment$1 near mark$1) with (image$1 or imaging$3)) and (mark$1 with (substrate$1 or semiconductor or (semi adj conductor$1) or wafer$1)) and pattern$1 and (mark$5 with reference$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 15:34
-	79	((alignment$1 near mark$1) with regist$8) and ((alignment$1 near mark$1) with (image$1 or imaging$3)) and (mark$1 with (substrate$1 or semiconductor or (semi adj conductor$1) or wafer$1)) and pattern$1 and (mark$5 with reference$1) and (mark$1 with (portion$1 or part$1 or partial$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 15:46
-	89	((alignment$1 near mark$1) with regist$8) and ((alignment$1 near mark$1) with (image$1 or imaging$3)) and (mark$1 with (substrate$1 or semiconductor or (semi adj conductor$1) or wafer$1)) and pattern$1 and (mark$5 with reference$1) and ((mark$1 or image$1) with (portion$1 or part$1 or partial$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:01